

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

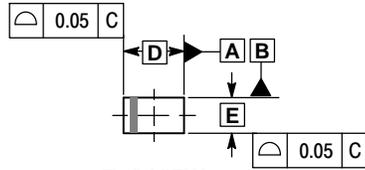
ON Semiconductor®



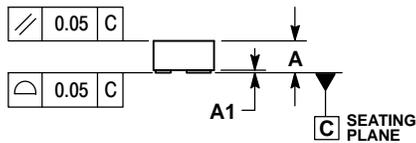
SCALE 8:1

DSN2, 1.0x0.6, 0.575P, (0402)
CASE 152AC
ISSUE D

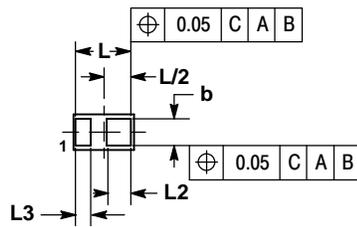
DATE 27 APR 2017



TOP VIEW

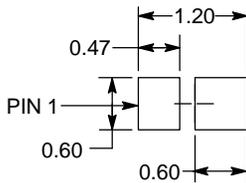


SIDE VIEW



BOTTOM VIEW

RECOMMENDED SOLDER FOOTPRINT*



DIMENSIONS: MILLIMETERS

See Application Note AND8464/D for more mounting details

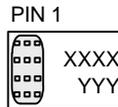
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

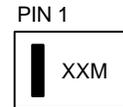
DIM	MILLIMETERS	
	MIN	MAX
A	0.25	0.31
A1	---	0.05
b	0.45	0.55
D	1.00	BSC
E	0.60	BSC
L	0.85	0.95
L2	0.35	0.45
L3	0.20	0.30

GENERIC MARKING DIAGRAM1*



XXXX = Specific Device Code
YYY = Year Code

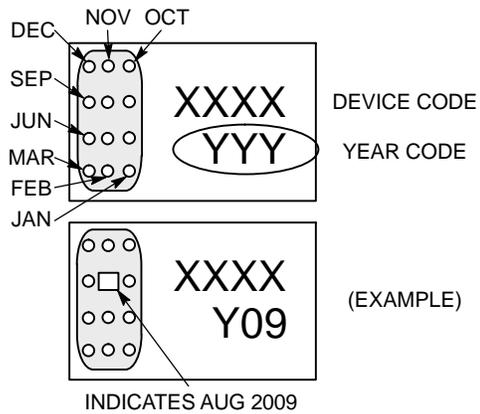
GENERIC MARKING DIAGRAM2*



XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

CATHODE BAND MONTH CODING



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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	DSN2, 1.0X0.6, 0.575P, (0402)	PAGE 1 OF 2

